

Sensors and Materials
Special Issue on
Materials, Devices, Circuits, Analytical Methods for Various Sensors
(Selected Papers from ICSEVEN 2019)

Call for Papers

The era of ubiquitous sensing has begun recently thanks to the rapid development of IoT. Sensors are essential components of automotive electronic systems used in modern applications including smart industries, smart cities, smart cars, robots, and smart buildings and homes. The aim of this issue will focus on all aspects of research and development related to sensor materials, sensor devices, sensor circuits, sensor readout circuits, sensor modules, sensor sub-systems or systems, and analytical software, deep learning and artificial intelligence (AI) for sensor and material applications. Sensor technology can also be applied to the management of related innovations about databases and network technologies in business.

We invite authors to contribute original research as well as comprehensive review articles on the recent progress in all kinds of materials, devices, circuits, analytical methods, and applications related to various sensors. Potential topics include, but are not limited to:

- Sensor materials
- Sensor devices and sensor arrays/Nano sensors/MEMS sensors
- Electrochemical sensors
- Microwave sensors
- Sensor applications for industry, medicine, bio-signal monitoring, environmental monitoring, corrosion, etc.
- Analytical methods, modeling, readout circuits and software for various sensors
- Deep learning and artificial intelligence (AI) for sensor and material applications.
- Sensor technology and new sensor principles
- Sensor technology applications and innovation issues related to management

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